

MATERIAL DECLARATION SHEET



Material Number	PTVS3-058C-TH			
Product Line	Semiconductor Products			
Compliance Date	December 12 th 2013			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.173000	Bisphenol Epoxy Resin	1675-54-3	40.00	4.80	12.01
				Epoxy Resin	25085-99-8	20.00	2.40	
				Crystalline Silica	14464-46-1	23.00	2.76	
				Brominated Epoxy Resin	40039-93-8	12.00	1.44	
				Iron Oxide	51274-00-1	2.00	0.24	
				Titanium Oxide	13463-67-7	3.00	0.36	
2	Electrodes	Copper	0.606763	Copper	7440-50-8	99.10	41.75	42.13
				Silver	7440-22-4	0.40	0.17	
				Other	-	0.50	0.21	
3	Terminations	Copper	0.502436	Copper	7440-50-8	99.50	34.71	34.88
				Other	-	0.50	0.17	
4	Termination Finish	Silver	0.002684	Silver	7440-22-4	100.00	0.19	0.19
5	Chip	Silicon Die	0.046696	Silicon	7440-21-3	85.91	2.79	3.24
				Aluminium	7429-90-5	4.93	0.16	
				Nickel	7440-02-0	8.73	0.28	
				Gold	7440-57-5	0.42	0.01	
6	Die Attach	Solder	0.046267	Lead	7439-92-1	92.50	2.97	3.21
				Tin	7440-31-5	5.00	0.16	
				Silver	7440-22-4	2.50	0.08	
7	Die Coating	Silicone	0.062442	Polysiloxane	63148-62-9	22.11	0.96	4.34
				Chromium Sesquioxide	1308-38-9	5.67	0.25	
				Fumed Silica	112945-52-5	11.11	0.48	
				Filler	Trade Secret	61.11	2.65	
		Total Weight	1.440289					